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U.S. UTILITY Patent Application

PATENT NUMBER and
ISSUE DATE

APPL NUM 10090142	FILING DATE 03/05/2002	CLASS 219	SUBCLASS 180.21	GAU 1725	EXAMINER EDMONDSON
**APPLICANTS: Miyazawa Ikuya;					
**CONTINUING DATA VERIFIED: <i>None - CRE</i>					
** FOREIGN APPLICATIONS VERIFIED: JAPAN 2001-75534 03/16/2001 - <i>CRE</i>					
PG-PUB <input type="checkbox"/> DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>			
Foreign priority claimed <input checked="" type="checkbox"/> yes <input type="checkbox"/> no 35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no Verified and Acknowledged Examiners's initials				ATTORNEY DOCKET NO 112155	
TITLE : Soldering method, soldering device, and method and device of fabricating electronic circuit module					

U.S. DEPT. OF COMM / PAT & TM-PTO-436L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
ISSUE FEE Amount Due Date Paid		DRAWING Sheets Drwg. Figs. Drwg. Print Fig.	
<input type="checkbox"/> TERMINAL DISCLAIMER		Primary Examiner PREPARED FOR ISSUE Application Examiner	
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